

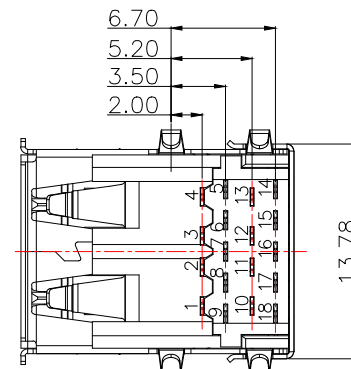
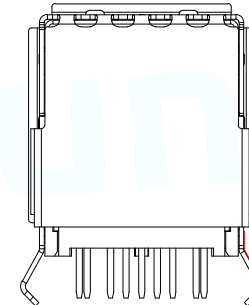
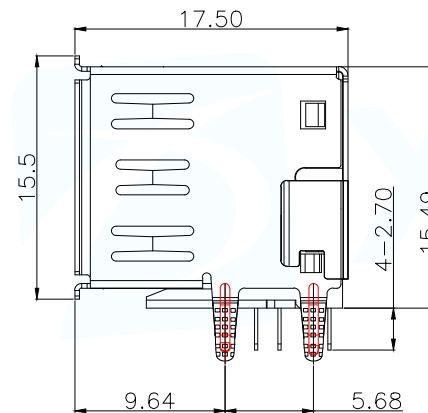
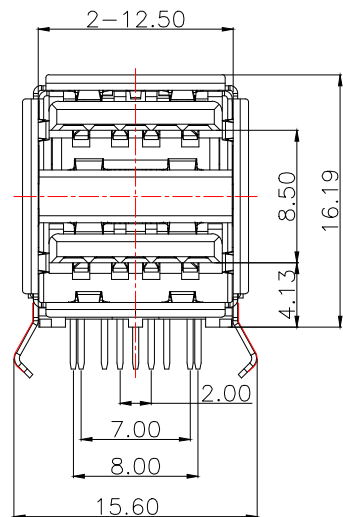
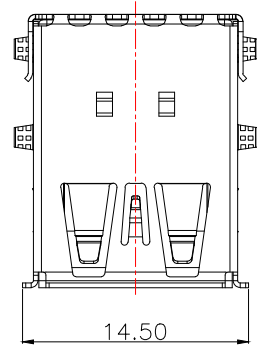
Remark:

1.MATERIAL:

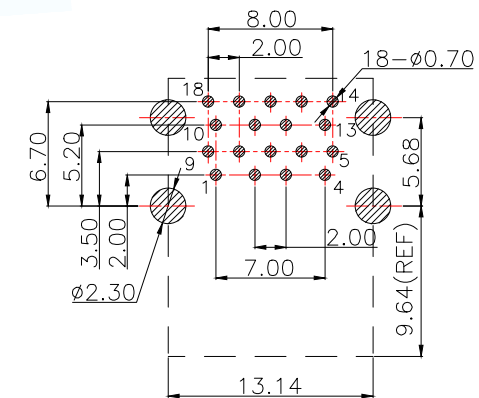
- 1.1 Housing:thermoplastic plastics.
- 1.2 terminals:Copper Alloy
- 1.3 Front Shell:Copper Alloy/SPCC.
Middle Shell:SPCC

2.characteristics:

- 2.1 Rating Voltage : 30V AC.
- 2.2 Rating Current:PIN1&PIN4(Vbus&Correponding ground PIN)
1.8A MAX Other PINS 0.25A min.
- 2.3 Contact Resistance:PIN1&PIN4:30 m Ω MAX. Other PINS: 50 m Ω
- 2.4 Insulation Resistance:100 M Ω MIN.
- 2.5 Withstanding Voltage:AC 100V between adjacent contacts
- 2.6 MECHANICAL CHARACTERISTIC:
INSERTION FORCE:35N MAX
EXTRACTION FORCE(INITIAL): 10N MIN
EXTRACTION FORCE(AFTER TEST):8N MIN
- 2.7 The lifting weight of the product before durability is 10N Min. 3s
- 2.8 Life test:1500Cycles MIN.
- 2.9 Temperature Range:-30 $^{\circ}$ ~+80 $^{\circ}$.



Pin Number	Signal Name	Pin Number	Signal Name
1	VBUS	10	VBUS
2	D-	11	D-
3	D+	12	D+
4	GND	13	GND
5	StdA_SSRX-	14	StdA_SSRX-
6	StdA_SSRX+	15	StdA_SSRX+
7	GND_DRAIN	16	GND_DRAIN
8	StdA_SSTX-	17	StdA_SSTX-
9	StdA_SSTX+	18	StdA_SSTX+
Shell	Shield		



PCB LAYOUT REFERENCE

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: USB 3.0 AF双层90度短体	
DECIMALS:		PAR	USB-303WSD-BRY
ANGLES:		DWN	Lucas
.X:±0.35		CHKD	Ethan
.XX:±0.25		APVD	Jacob
.XXX:±0.10		SCALE:1:1	UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1